

LTspice Model Photo Coupler Renesas PS2501L-1-F3-A

Model Information

Model A macro model

Call Name MDC_PS2501L-1-F3-A_LT

Pin Assign 1:Anode 2:Cathde 3:Emitter 4:Collector

File List Model Library MDC_PS2501L-1-F3-A_LT.lib

Model Report MDC_PS2501L-1-F3-A_LT.pdf(this file)

Verified Simulator Version LTspice v24.0.12

Note

References

The information which was used for modeling is as follow:

[Data Sheet]

● Date/Version Dec 25, 2020 / Rev.1.00

Product name
PS2501L-1-F3-A

Company name
Renesas Electronics Corporation

[Characteristics listed]

● Characteristics IF-VF

IC-VCE-IF VTR-IF

Switching Time vs. LOAD RESISTANCE

Simulation Condition

This table shows the range of evaluated simulation range that was not occurs any convergence problems in this area.

Item	Condition	Unit
Temperature	25	deg C





Model Functions Table

Photo coupler

O:Implemented

×: Not Implemented

—: Not applicable

RANK=1

Functions	RANK	Implemented
IF-VF-Temp	1	0
Iout-Vout-IF	1	0
Iout-IF	1	
Iout/IF-IF(CTR-IF)	1	0
CJ-VR	1	_
Propagation delay	1	_
Switching (Typ.)	1	0

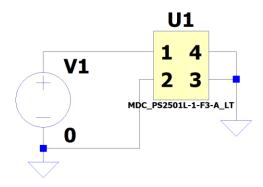


IF-VF Testbench

Referred to Data Sheet

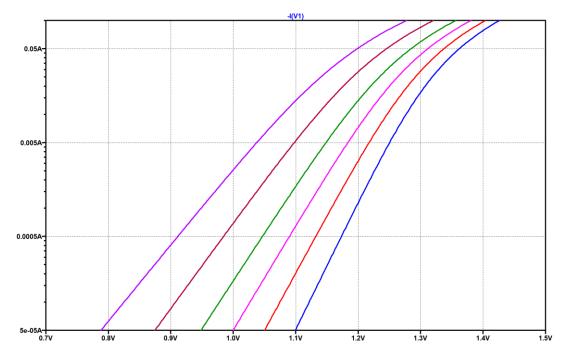
.OPTION TNOM=25 .TEMP -50 -25 0 25 60 100

.dc V1 0.7 1.5 0.01



Simulation results are following. Explanatory notes — : simulated

IF-VF



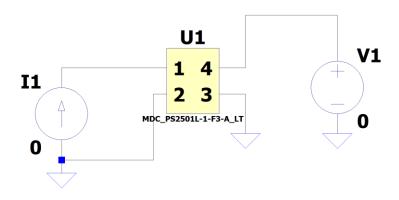


IC-VCE Testbench

Referred to Data Sheet

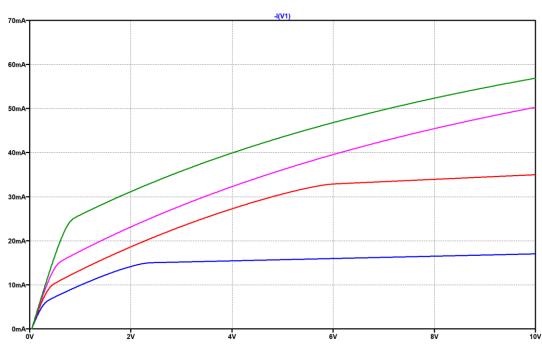
.OPTION TNOM=25 .TEMP 25

.dc V1 0 10 0.01 I1 list 5m 10m 20m 50m



Simulation results are following. Explanatory notes — : simulated

IC-VCE



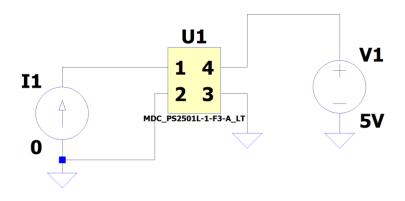


CTR-IF Testbench

Referred to Data Sheet

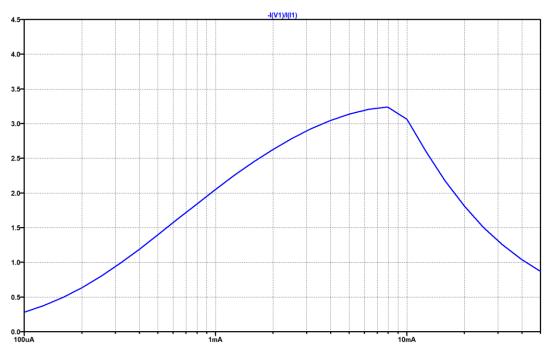
.OPTION TNOM=25 .TEMP 25

.dc dec I1 0.1m 50m 10



Simulation results are following. Explanatory notes — : simulated

CTR-IF

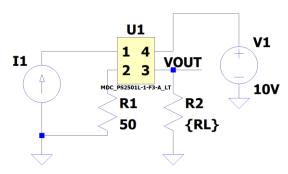


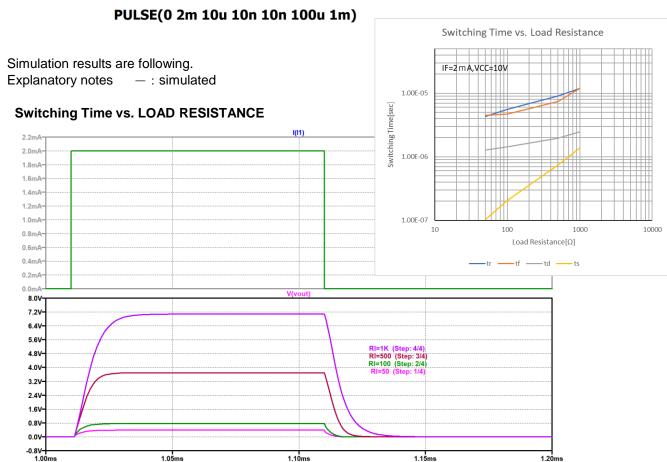


Switching Time vs. LOAD RESISTANCE Testbench

Referred to Data Sheet

- .step param RL list 50 100 500 1k
- .OPTION TNOM=25
- **.TEMP 25**
- .tran 1.5m







DISCLAIMER

- 1. This SPICE (Simulation Program with Integrated Circuit Emphasis) model and its content (the "Contents") are copyright of MoDeCH Inc. All rights reserved. Any redistribution or reproduction of any or all part of the Contents in any form is prohibited without express written permission made by MoDeCH Inc.
- MoDeCH Inc. as licensor (the "Licensor") hereby grants to you, as licensee (the "Licensee"), a nonexclusive, non-transferable license to use the Contents as long as you abide by the terms and conditions of this DISCLAIMER.
- 3. The Licensee is not authorized to sell, loan, rent and redistribute or license the Contents in whole or in part, or in modified form, to anyone.
- 4. The Licensor shall in no way be liable to the Licensee or any third party for any loss or damage (including ,but not limited to, lost profits, or other incidental, consequential, or punitive damages), however caused (including through negligence) which may be directly or indirectly suffered from, arising out of, or in connection with, any use of the Contents.
- 5. Notwithstanding anything contained in this DISCLAIMER, in no event shall Licensor be liable for any claims, damages or loss which may arise from the modification, combination, operation or use of the Contents with the Licensee's computer programs.
- 6. The Licensor does not warrant that the Contents will function in any environment.
- 7. The Contents may be changed or updated without notice. MoDeCH Inc. may also make improvements and/or changes in the products, pricing and/or the programs related to the Contents at any time without notice.



MoDeCH Inc.

Head Office

Location: 5-15 Yokoyama-cho, Hachioji-Shi, Tokyo 192-0081, Japan

Tel:+81-42-656-3360

E-Mail:model-on-support@modech.co.jp

URL:http://www.modech.com/en/